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SiGe formation by Ge implant+high power Anneal Raman data summary

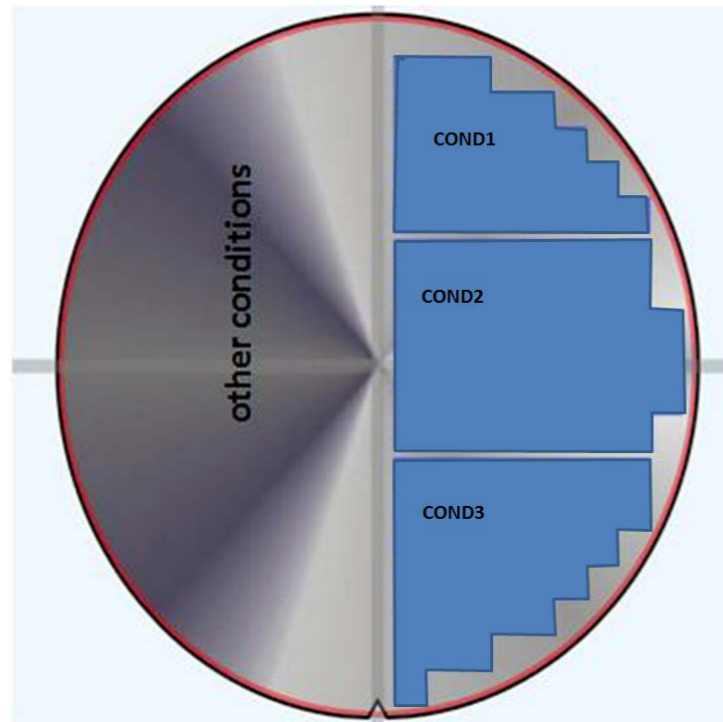


- Background: samples conditions, TEM and SIMS analysis
- Raman analysis: set-up and reference data
- Example of Raman spectrum
- Analysis position
- Summary of center analysis
- Focus on wf 01 and wf 02
- Summary of edge analysis
- Summary of cross line and depth profile analysis
- Focus on wf 05 COND1, COND2, COND3
- Conclusions

Process conditions:

Ge implant	Ge anneal	wf#
50 keV 3.5 E17 atoms/cm ²	High temp – single step	01
50 keV 5E17 atoms/cm ²	High temp – double step	02
50 keV 3.5 E17 atoms/cm ²	laser anneal	05

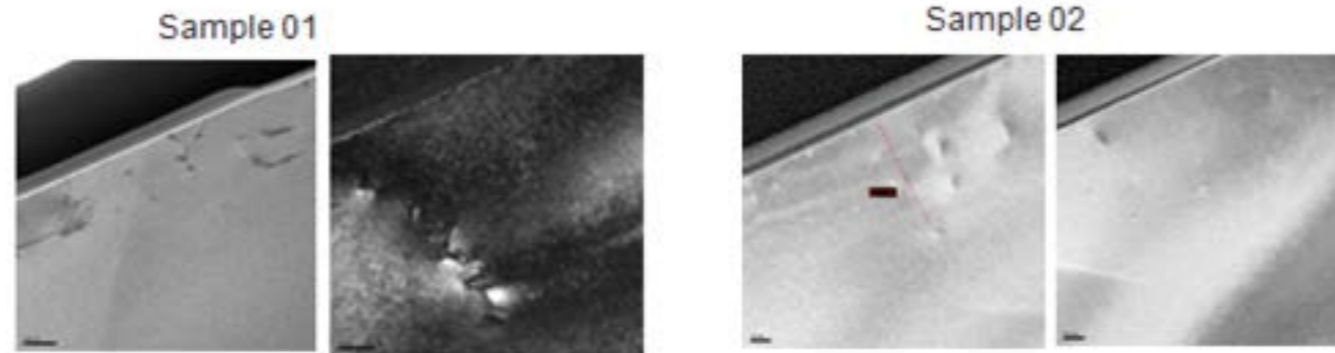
Focus on wf 05: laser thermal annealing



COND 1	COND 2	COND 3
2X	3X	30X

Relative energy density, for each condition

■ Wf 01 and wf 02

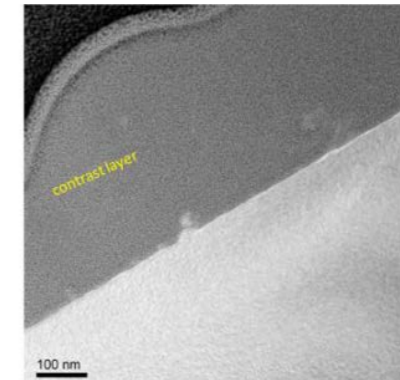
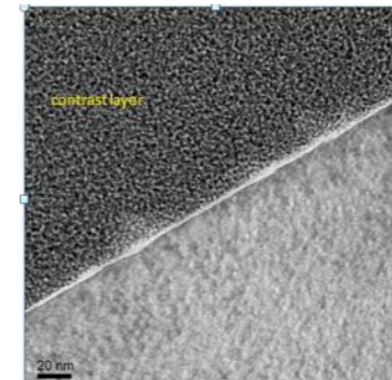


Residuals extended defects are observed when single furnace is used; Better results are observed on sample 02 (double anneal)

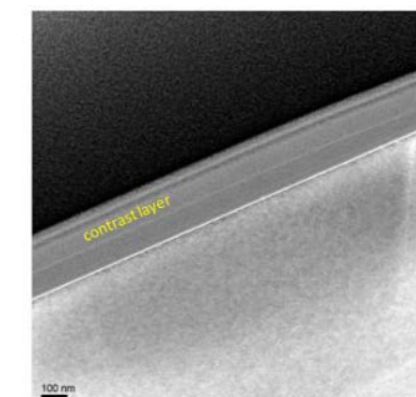
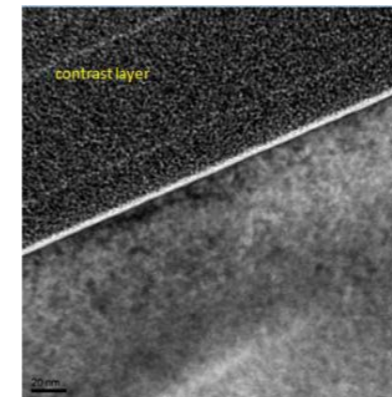
■ wf 05

- COND1 sample shows defects and silicon extrusions in the silicon surface; the bulk lattice is well crystallized;
- COND2 and COND3 both show a good silicon crystallization;
- All the three sample show an oxide layer grown in the silicon surface.

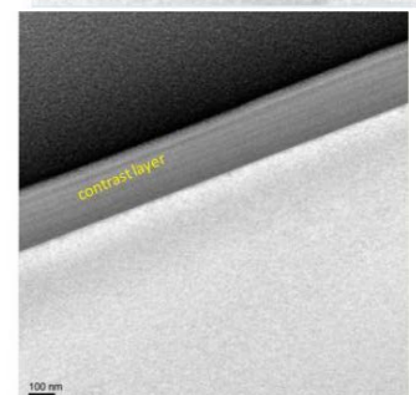
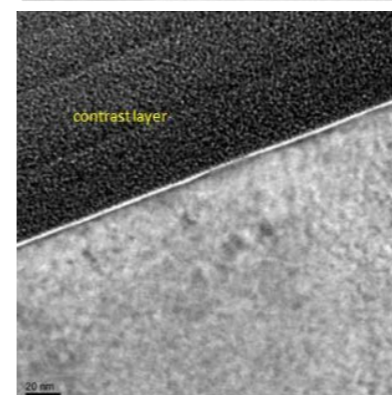
Cond 1

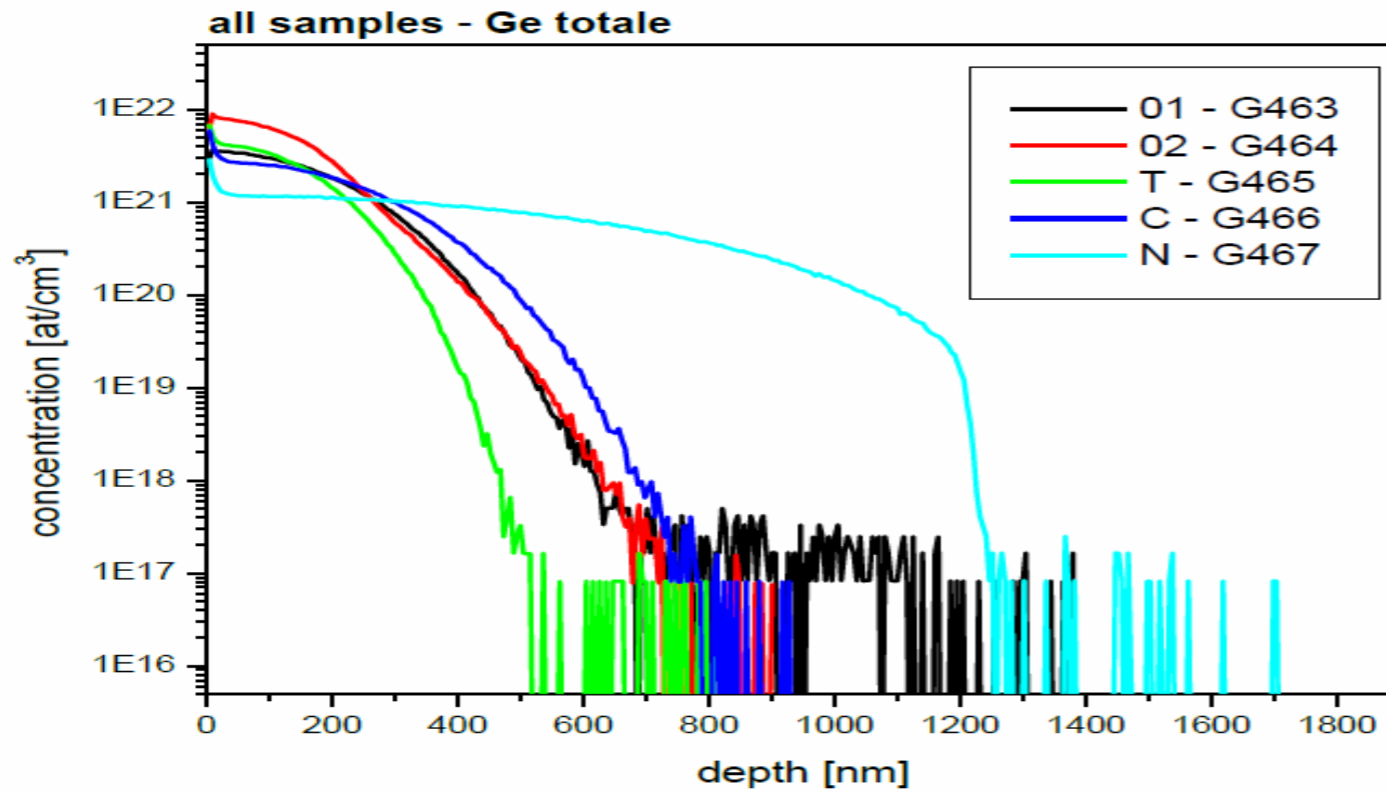


Cond 2

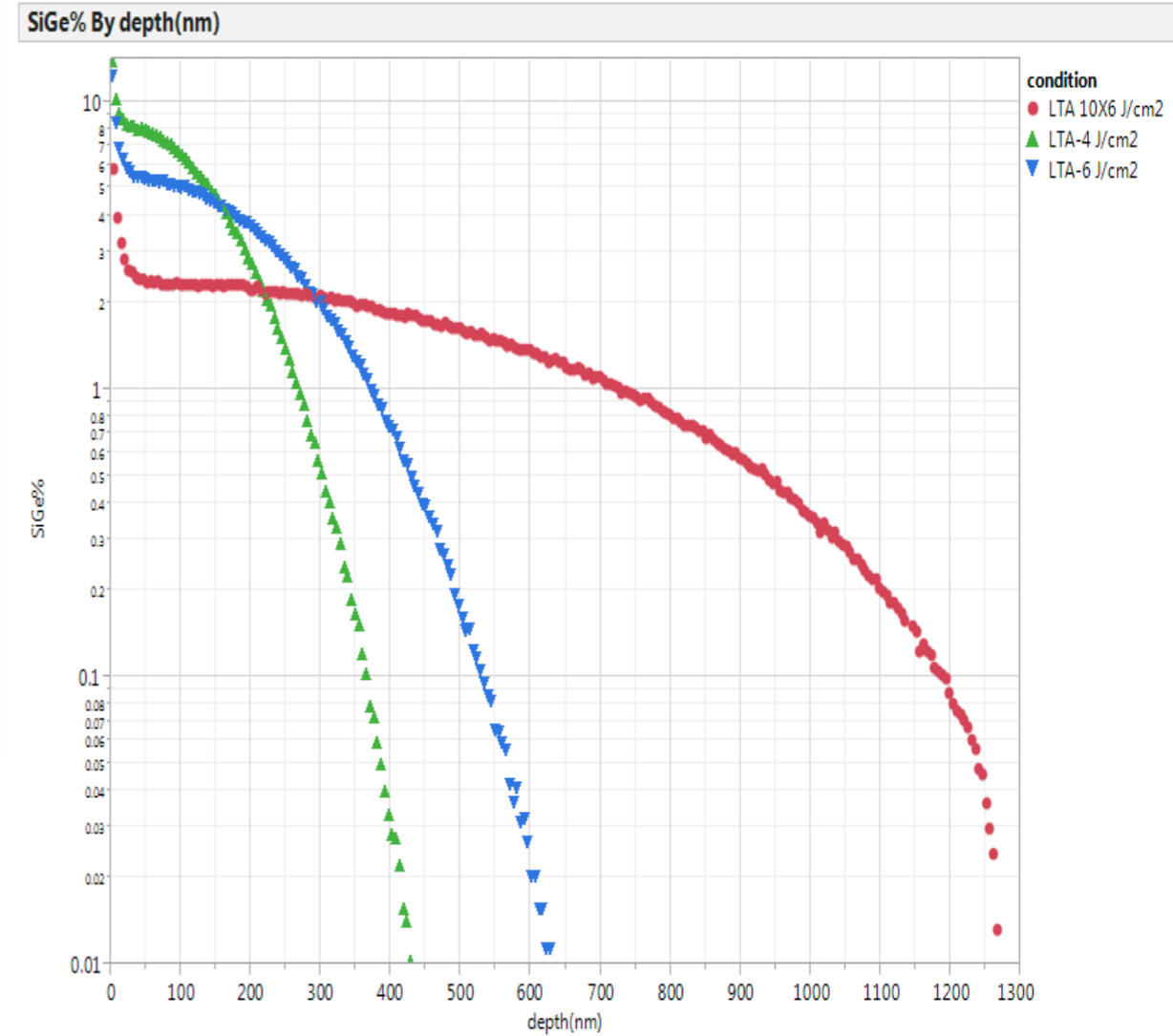


Cond 3





The total calculated dose is systematically lower than the implanted one;
 The samples annealed in furnaces (01, 02) show Ge diffusion with a concentration greater than 10^{22} up to a depth of 400/600 nm;
 Deeper Ge diffusion is obtained by using LTA;
 the sample N (condition LTA3) showed a Ge diffusion of about 1 μm

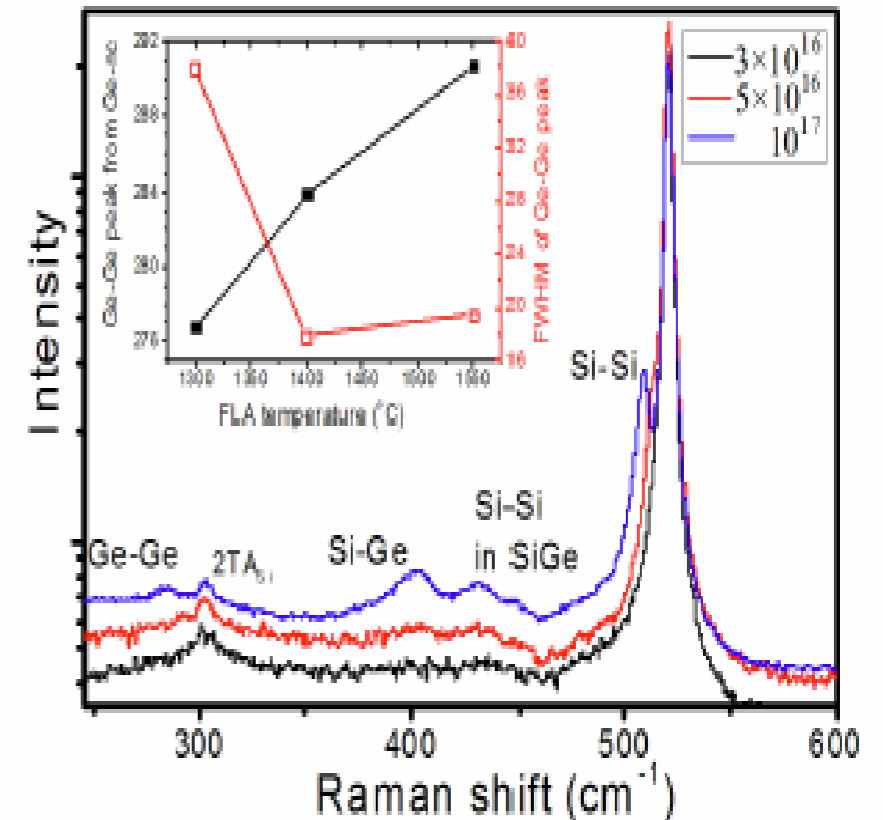


sample	SIMS Ge dose at/cm ²
Wf 01	$(7.4 \pm 0.7) \text{ E } 16$
Wf 02	$(1.4 \pm 0.1) \text{ E } 17$
Wf 05 Cond1	$(7.2 \pm 0.7) \times 10^{16}$
Wf 05 Cond2	$(7.3 \pm 0.7) \times 10^{16}$
Wf 05 Cond3	$(7.6 \pm 0.7) \times 10^{16}$

Density of silicon $4.995\text{E}+22$ Atoms/cm³

Ge concentration at the surface ~ 10% in wf 01, ~20% in wf 02, ~10-5% in wf 05.

- UV (355 nm) and Green (532 nm) Laser were used
- Objective lens: UV 40x – Green 100x
- Laser power: UV 50% – Green 10%
- Penetration Laser: ~510 nm for Green laser, ~10 nm for UV laser
- Type of measurement: StreamLine range 400nm-1800 nm, Depth profile range 1,9um-2,9 um
- Silicon lattice: Diamond Cubic. Lattice spacing: 0,543 nm
- Germanium lattice: Diamond Cubic. Lattice spacing: 0,566 nm
- Lattice mismatch: $\epsilon = (|a_{Si} - a_{Ge}|/a_{Si}) * 100 = 4.2\%$



□ From reference	Peak position Si-Si bulk	520,5 cm ⁻¹
	Peak position Si-Si in SiGe	508 cm ⁻¹
	Peak position Si-Ge in SiGe	403 cm ⁻¹
	Peak position Ge-Ge	286 cm ⁻¹

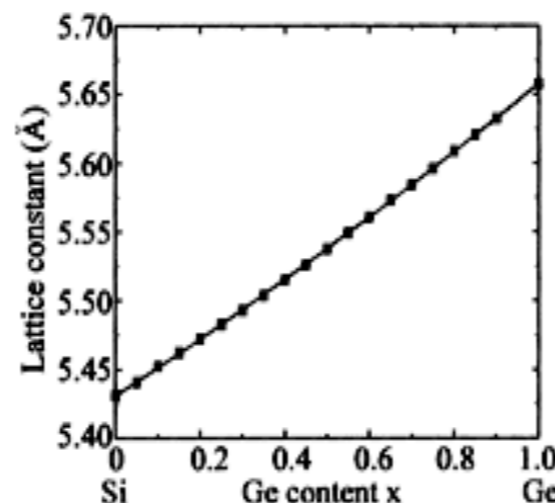
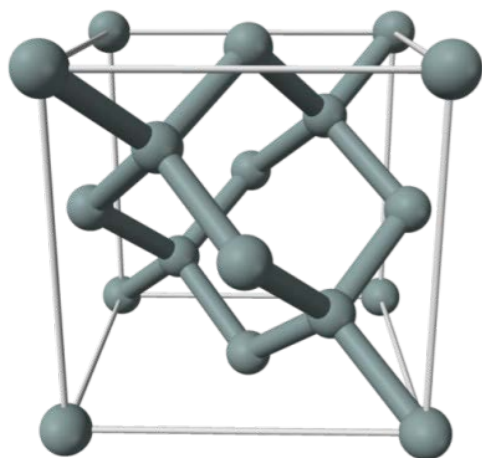
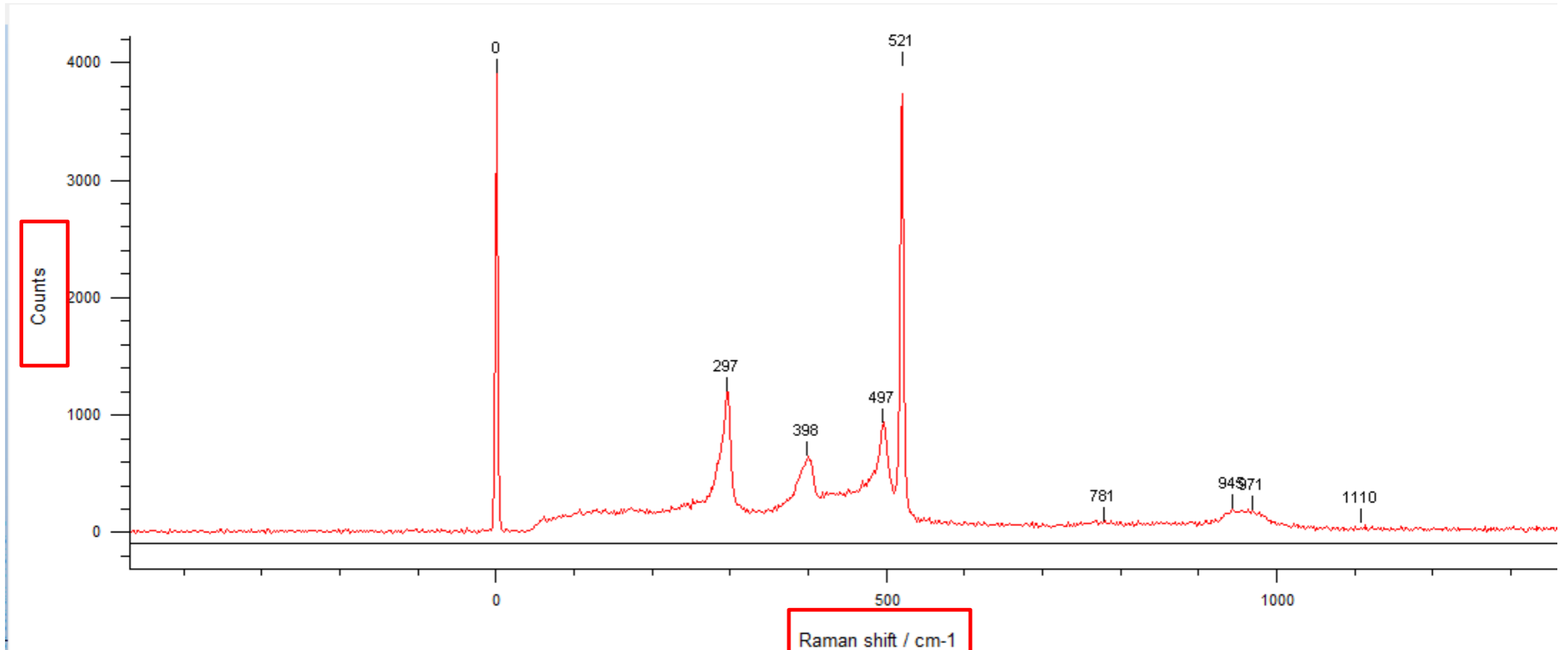


Fig. 2. μ -Raman spectra obtained from the flash lamp annealed samples for 20 ms at 1400 °C. Several characteristic peaks of Si_{1-x}Ge_x are clearly depicted. The inset shows the change of the Ge-Ge related phonon mode position and FWHM as the function of annealing temperature.

Reference: Fabrication of SiGe alloy on Silicon by Ge-Ion-Implantation and Short-Time-Annealing, K.Gao et al., Acta phys. Pol. Vol 123 (2013)

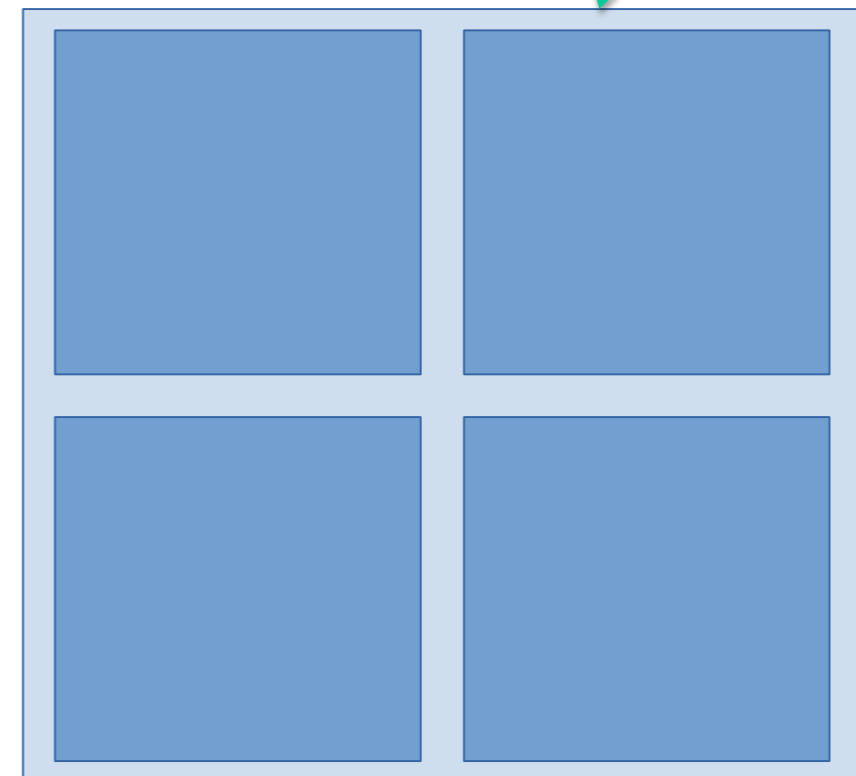
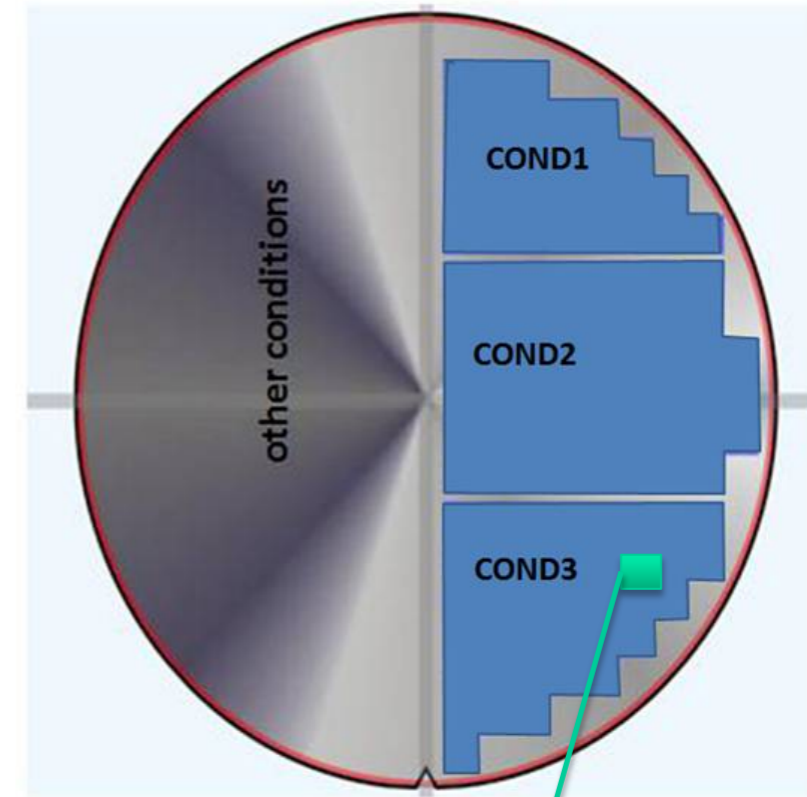
Example of Raman Sprectrum



Peak no.	Centre	Height	Width	Area	Absolute inten...	Low edge	High edge
2	0.22455	3931.08	2.36497	11523.2	3942.92	-13.6465	15.9531
5	296.945	1005.53	12.8394	51151.1	1208.94	248.91	330.768
6	398.495	388.107	20.2412	46281.1	659.827	338.34	417.422
7	496.847	582.443	11.399	53818	949.028	445.477	508.707
8	520.813	3727	4.4627	34582.4	3999.22	510.559	545.668
10	780.965	34.1019	3.48693	3115.52	103.207	772.863	792.549
11	944.882	53.3498	3.4744	12367.5	209.95	904.357	953.545
12	971.251	46.6173	3.16284	12921.8	196.035	955.297	1000.69
13	1109.67	54.28	6.85547	581.256	92.8876	1118.18	1125.04

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- For the wafer 01 and 02 (without any pattern) the analysis was taken at the center of the wafer;
- For the wafer 05 the analysis was taken in different points of the pattern. The pattern is made with several squares (of the order of $\sim 1-10 \text{ cm}^2$), due to the laser annealing process.



- **Positions of the analysis:**

- Center
- Edge
- Crossline
- Depth profile

GREEN LASER:

- ➔ wf 05 COND1 and wf 05 COND2: only the Si-Si peak is visible.
- ➔ Wf 01: the Si-Ge is weakly visible around 390 cm^{-1}
- ➔ wf 05 COND3: the Si-Si peak, the Si-Ge peak and the Ge-Ge peak.
- ➔ *The wf 02 is the only sample that shows all the peaks similar to the reference.*
- ➔ The width of the Si-Si peaks are narrow (between 7 and 5) and decrease increasing the thermal power in the process condition

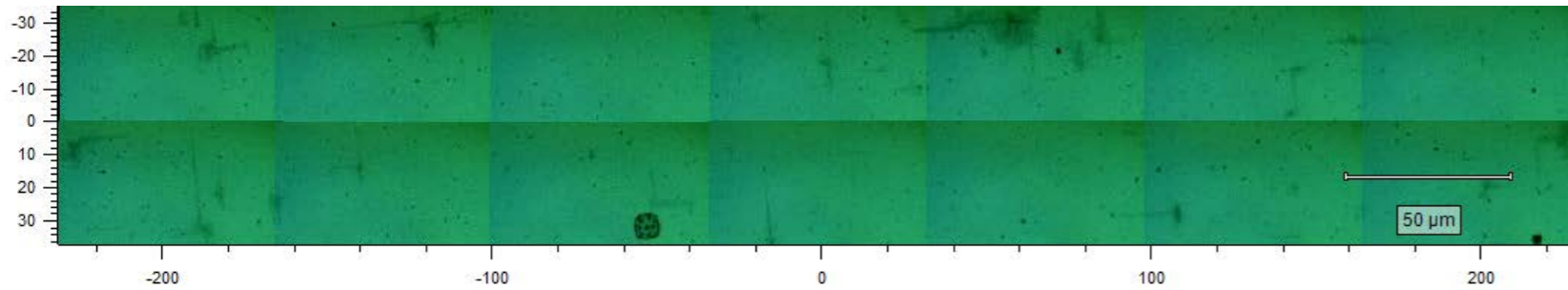
wf	Process condition	# peak	Peak position (Raman shift cm^{-1})
Wf 02	High temp - double step	1 st	302,585
		2 nd	401,39
		3 rd	512,52
		4 th	520,58

UV LASER:

- ➔ Only one peak is visible for each sample.
- ➔ Every peak shows a very large width (between 60 and 25) revealing amorphous phases.

wf	Process condition	Peak position (Raman shift cm^{-1})
01	High temp – single step	513,285
02	High temp – double step	507,401
05 COND1	Laser anneal 2x	515,704
05 COND2	Laser anneal 3x	514,345
05 COND3	Laser anneal 30x	516,929

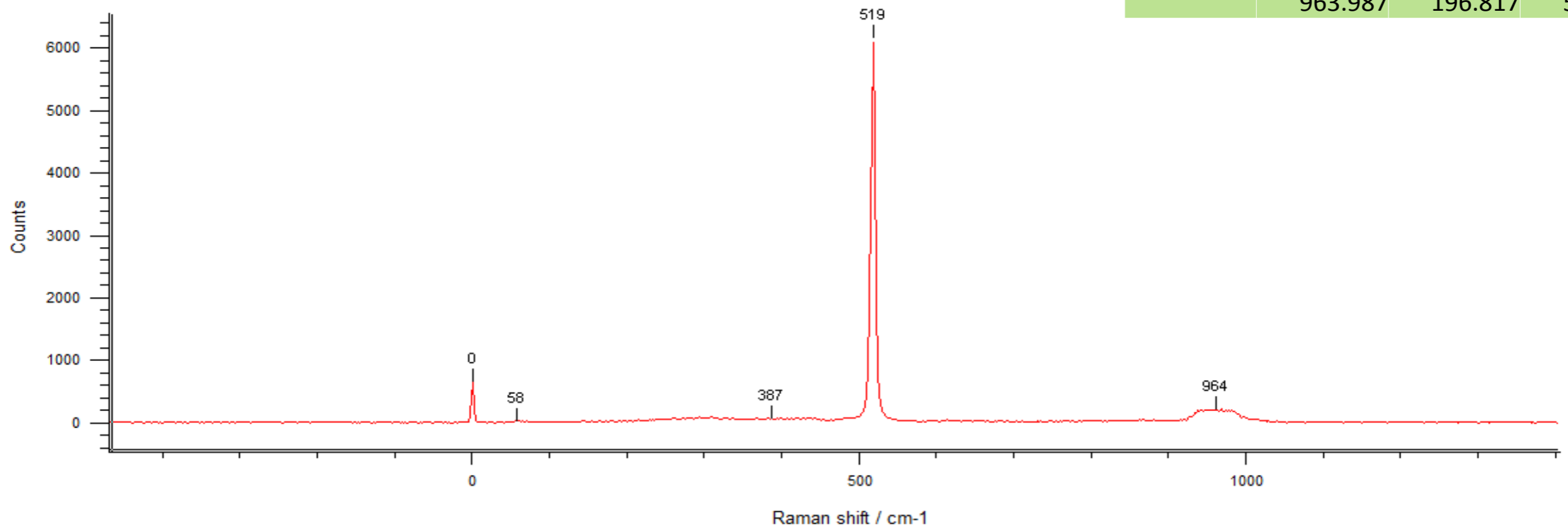
From reference article	Peak position Si-Si bulk	520,5	Peak position Si-Ge in SiGe	~400
	Peak position Si-Si in SiGe	~500	Peak position Ge-Ge	~300



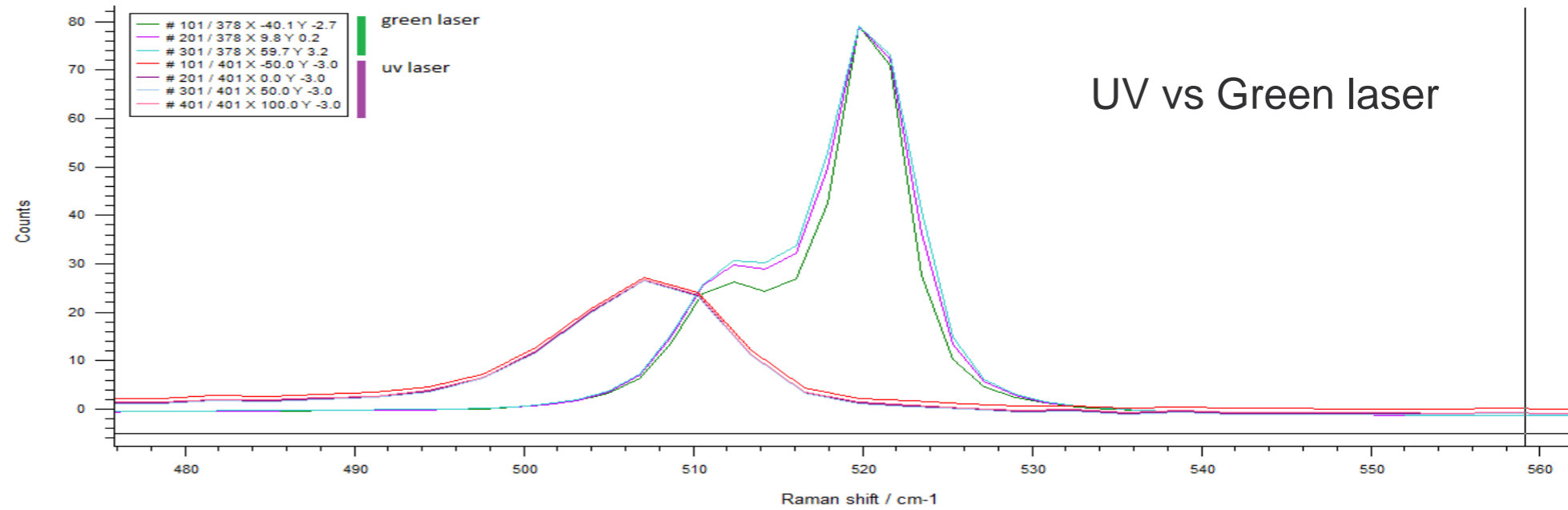
- Process condition: Ge implantation + furnace annealing
- Measurement: streamLine 200 um, step 0.5 um, 1 sec exposure time

UV	Peak Position	Height	Width
	513.285	40.4998	9.17186
GREEN	Peak Position	Height	Width
	0.17377	486.68	2.97384
	57.873	23.6508	6.97217
	387.376	29.1492	2.22819
	519.231	6169.36	7.03638
	963.987	196.817	57.9348

Raman spectrum of wf 01 (green laser)

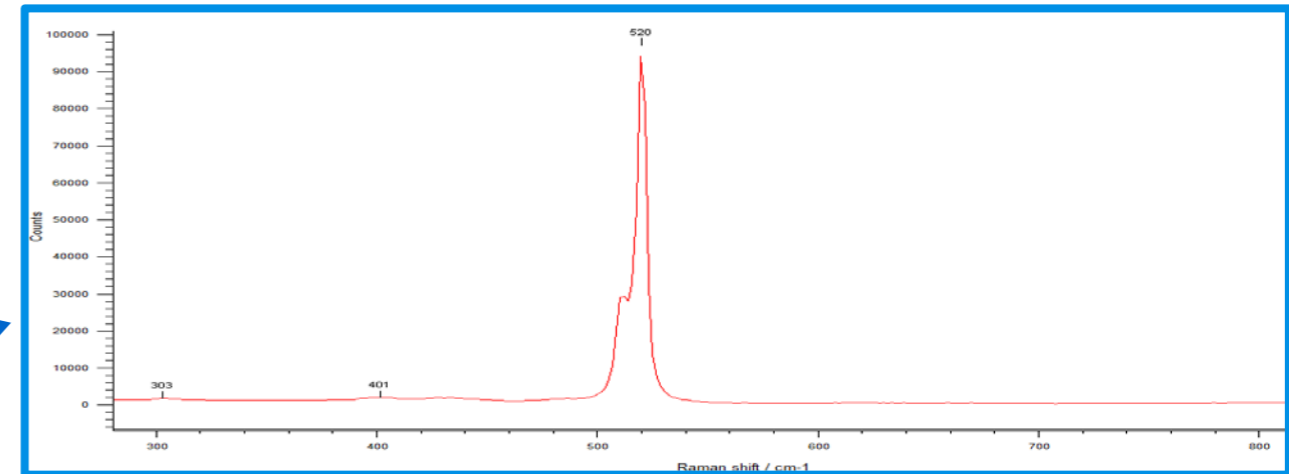
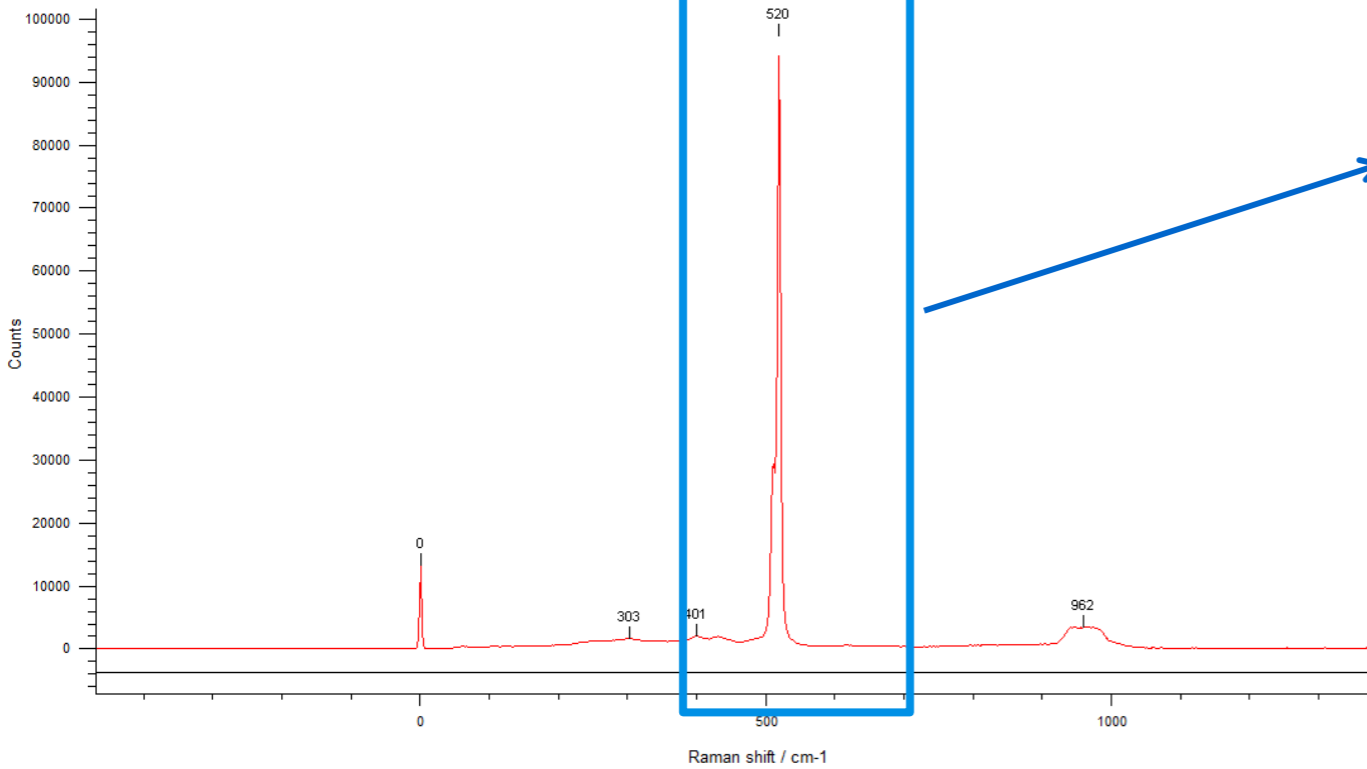


- Process condition: Ge implantation x2 + furnace annealing x2
- Measurement: streamLine 200 um, step 0.5 um, 1 sec exposure time



UV vs Green laser

Raman spectrum of wf 02 (green laser) and zoom of the main peak:



	Peak position	Width	Height
Green curve 1	520,583	6,04101	96338,77
Green curve 2	512,521	7,86846	3884,498
Green curve 3	302,585	37,253	717,825
Green curve 4	401,39	26,83	805
UV	507,401	9,58473	28,4308

Peak no.	Centre	Height	Width	Area	Absolute inten...	Low edge	High edge
12	0.19572	10632.9	2.93024	78686.8	13324.8	-25.5156	2.1543
13	302.595	717.825	37.253	430525	1733.13	47.4063	349.686
14	401.39	805.639	16.8339	270660	2064.15	351.576	447.344
15	520.475	96794.9	5.29261	1.10228e+006	97740.9	449.211	598.959
18	962.34	3294.69	62.3543	422274	3454.54	727.941	1088.97

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GREEN LASER:

- ➔ COND1, COND2 and COND3 show all the peaks in areas similar to the reference.
- ➔ The width of Si-Si bulk peaks is narrow and close to 4. The other peaks show broader width.

UV LASER:

- ➔ COND1 shows only one peak, really close in value to the Si-Si in SiGe peak, and very large in width.
- ➔ COND2 and COND3 shows two peaks with narrow width

wf	Process condition	Peak position (Raman shift cm^{-1})
05 COND2	Laser anneal 3x	511,424
		495,099
05 COND3	Laser anneal 30x	495,579
		509,158

From reference article	Peak position Si-Si bulk	520,5	Peak position Si-Ge in SiGe	~400
	Peak position Si-Si in SiGe	~500	Peak position Ge-Ge	~300

GREEN LASER for Cross-line:

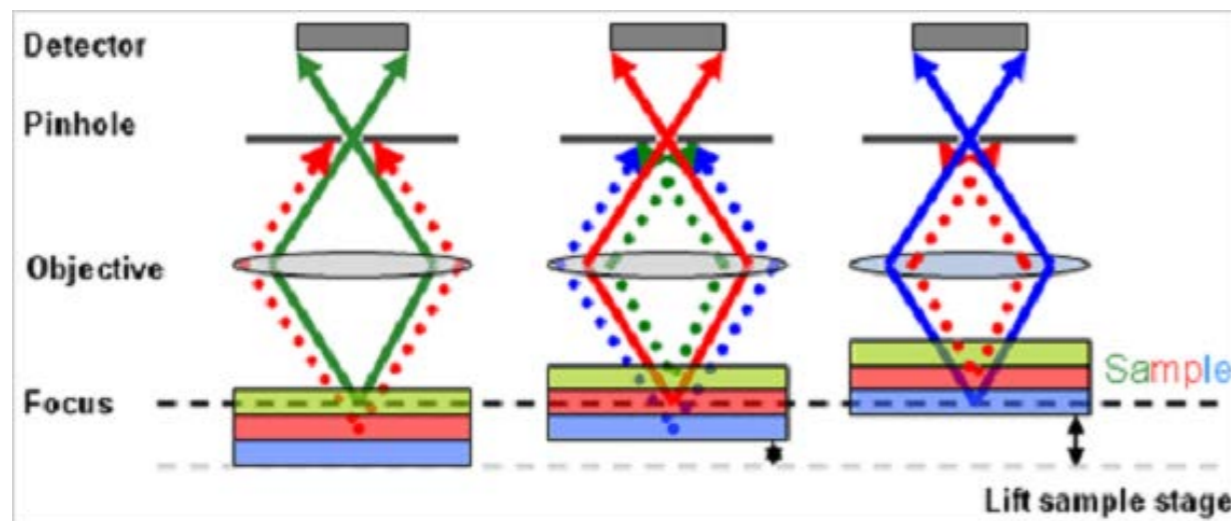
- ➔ The width of the edge's square slowly decreases, increasing the power of laser annealing. In the COND3 the squares are overlapped.
- ➔ The peaks follow the same trend depending on position. The change in width of all the peaks shows the amorphous phase along the edge.

GREEN LASER for Depth-profile:

- ➔ The width and the position remain constant and the intensity decreases with the increasing Z. The intensity of Si-Si peak is more than the others.

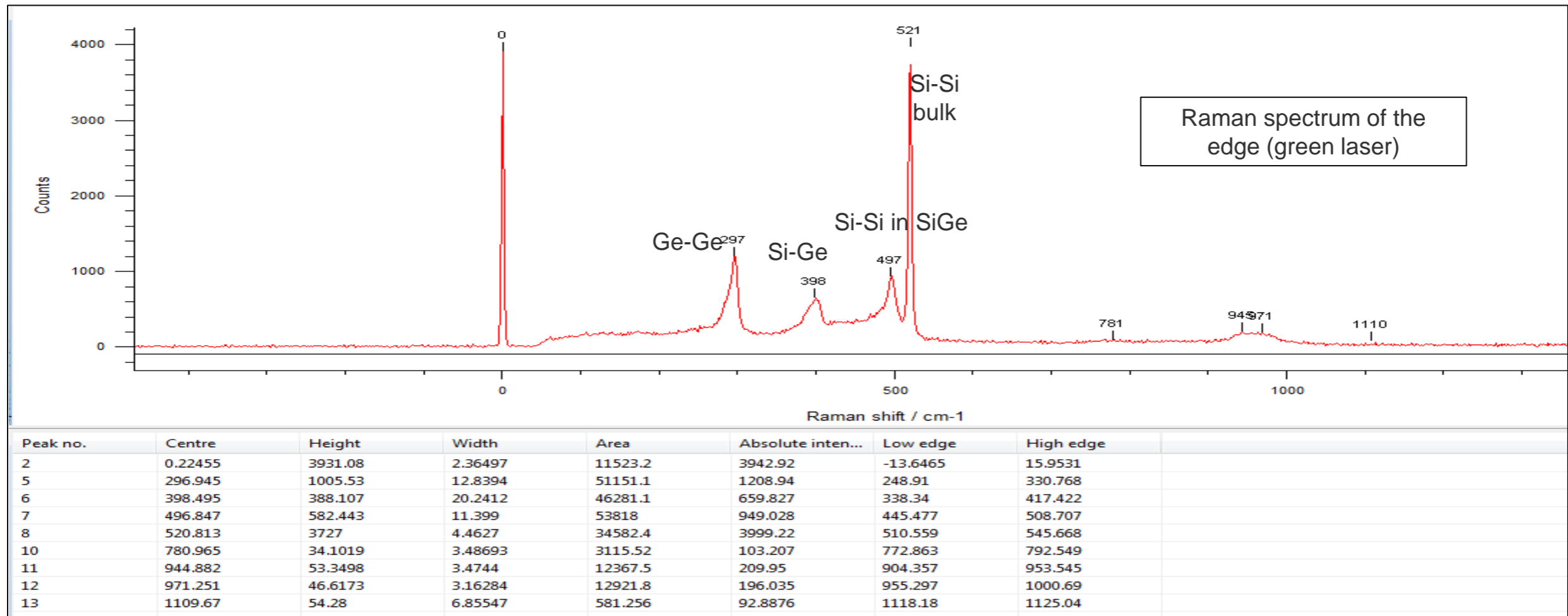
UV LASER:

- ➔ The peaks in cross line measurements show the same trend of green laser measurements.



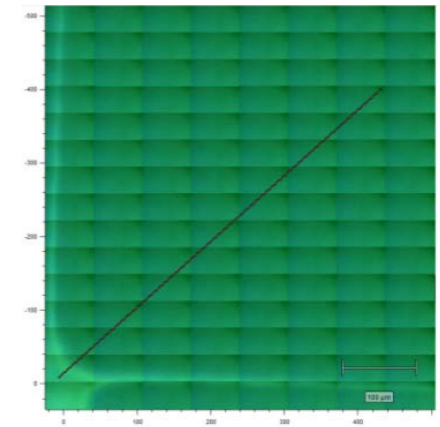
From reference article	Peak position Si-Si bulk	520,5	Peak position Si-Ge in SiGe	~400
	Peak position Si-Si in SiGe	~500	Peak position Ge-Ge	~300

- Process condition: Ge implantation + Laser anneal 2x
- Measurement:
 - center square, streamLine1000 um, step 1 um, exposure time 1s
 - edge square, streamLine 900 um, step 5 um, exposure time 1s
 - crossline, streamLine 400 um, step 0.5 um, exposure time 1s
 - depth profile, step 0.1 um, exposure time 1s, Z center 1,9 um, Z edge 2,9 um

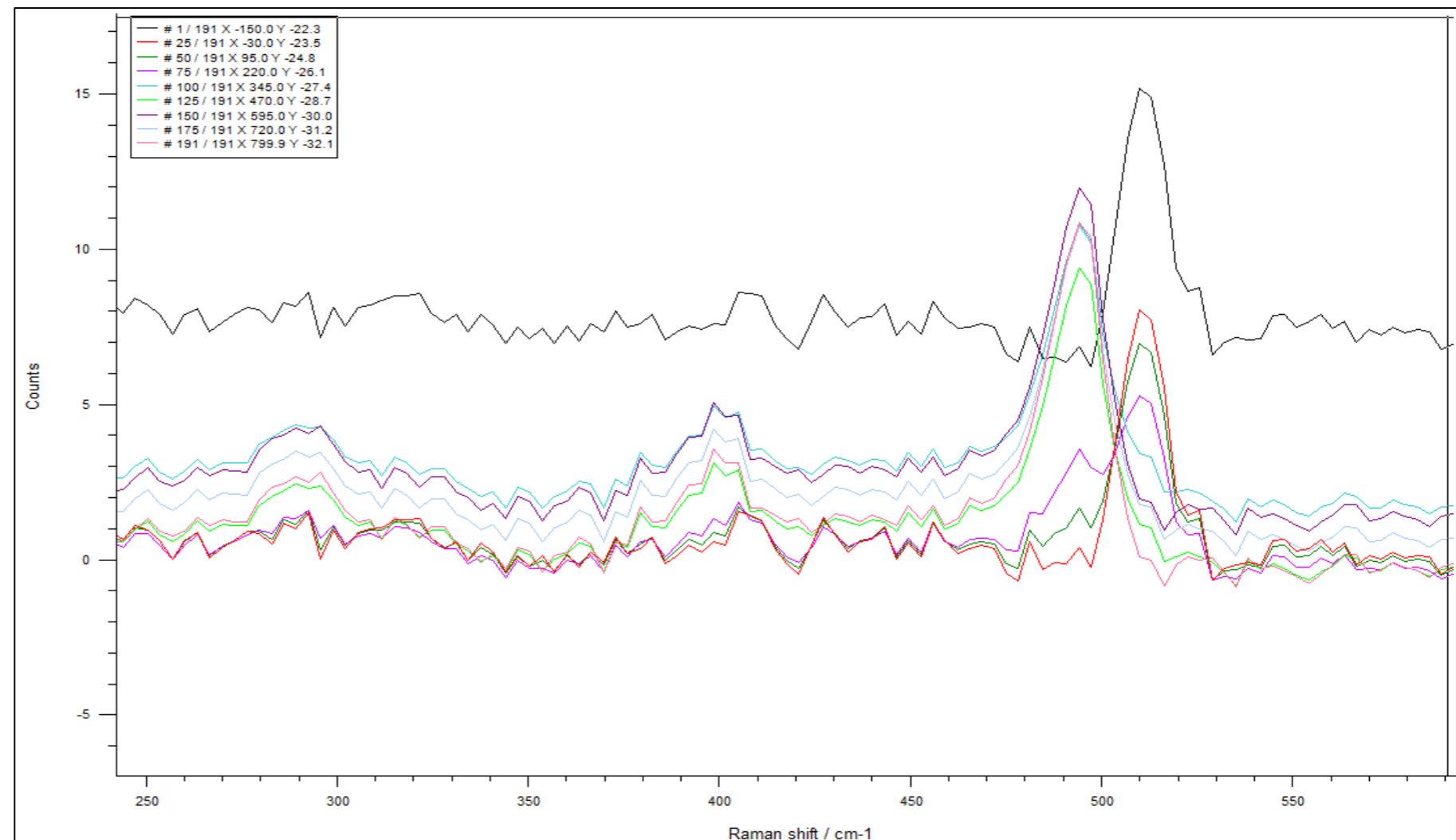


CROSS LINE: width vs distance
Width of the Silicon peak

- Process condition: Laser anneal 3x
- Measurement:
 - center square, streamLine1000 um, step 1 um, exposure time 1s
 - edge square, streamLine 900 um, step 5 um, exposure time 1s
 - crossline, streamLine 400 um, step 0.5 um, exposure time 1s
 - depth profile, step 0.1 um, exposure time 1s, Z center 1,9 um, Z edge 2,9 um



Evolution spectra from center to corner (UV laser):

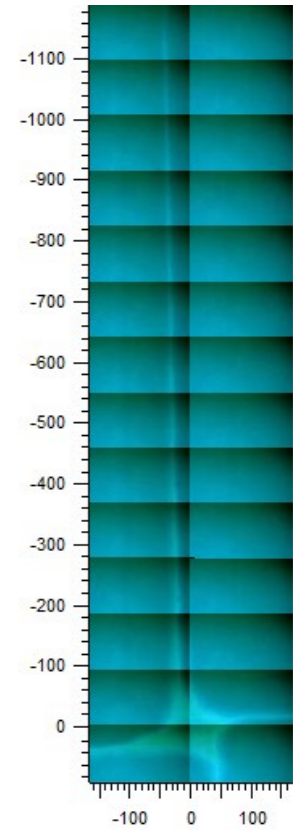


■ Depth profile (green laser only)

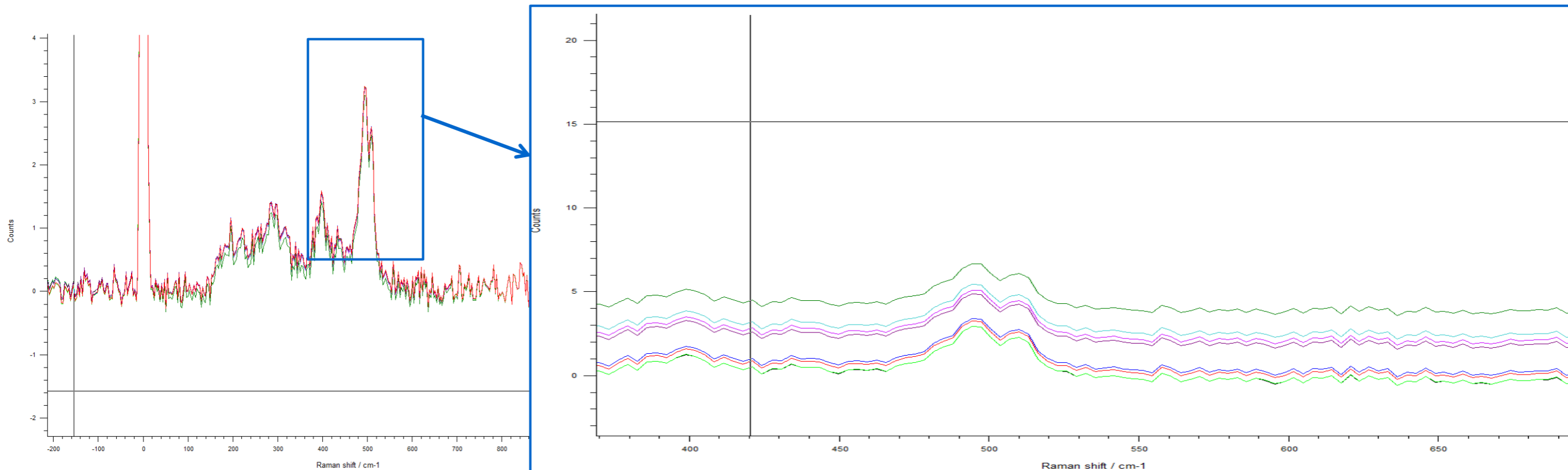
Only the intensity decreases with the increasing Z.

	Peak position
Curve 1 edge	294,238
Curve 2 edge	501,167
Curve 3 edge	401,934
Curve 4 edge	520,114
Curve center	519,437

- Process condition: Laser anneal 30x
- Measurement:
 - center square, streamLine1000 um, step 1 um, exposure time 1s
 - edge square, streamLine 900 um, step 5 um, exposure time 1s
 - crossline, streamLine 400 um, step 0.5 um, exposure time 1s – Near Corner (200 um UV/120 um Green) and Far Corner (2000 um UV/1200 um Green)
 - depth profile, step 0.1 um, exposure time 1s, Z center 1,9 um, Z edge 2,9 um

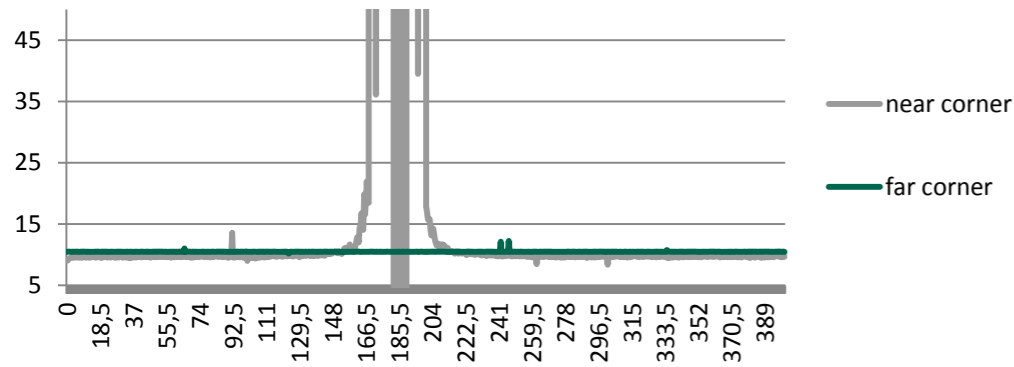


Evolution spectra from center to corner (UV laser):

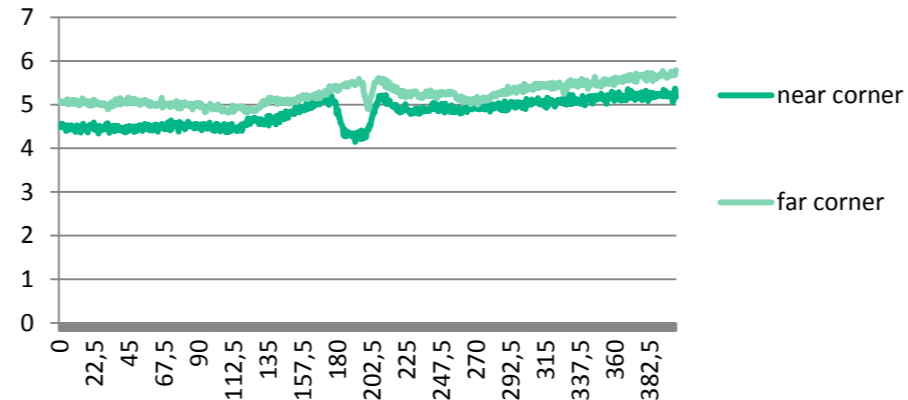


Cross line: In the UV crossline there are differences between the edge and the square only for near corner, in the Green spectra there are differences for both of the crosslines.

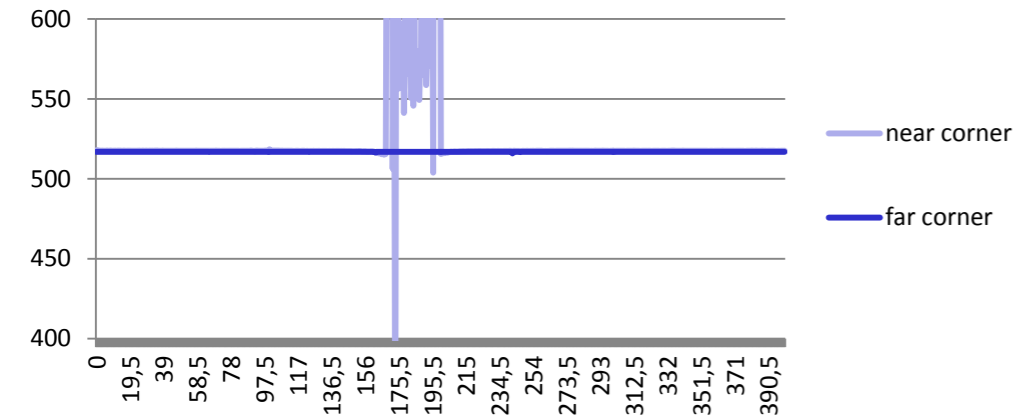
Width UV



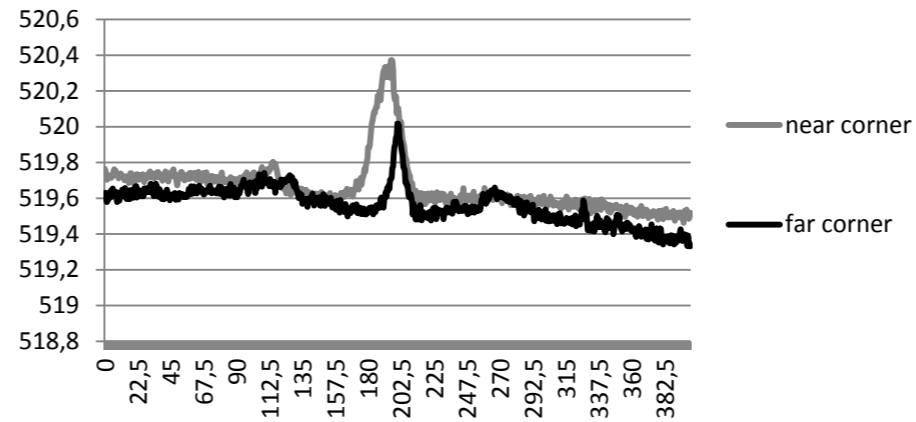
Width green



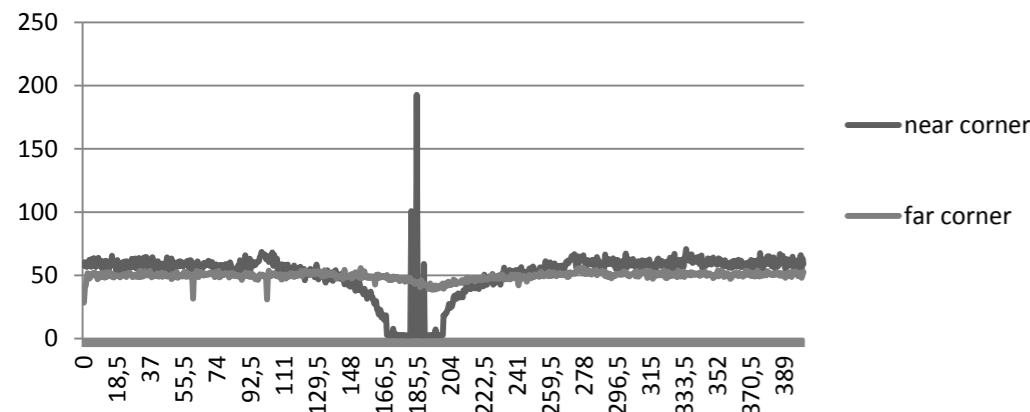
Position UV



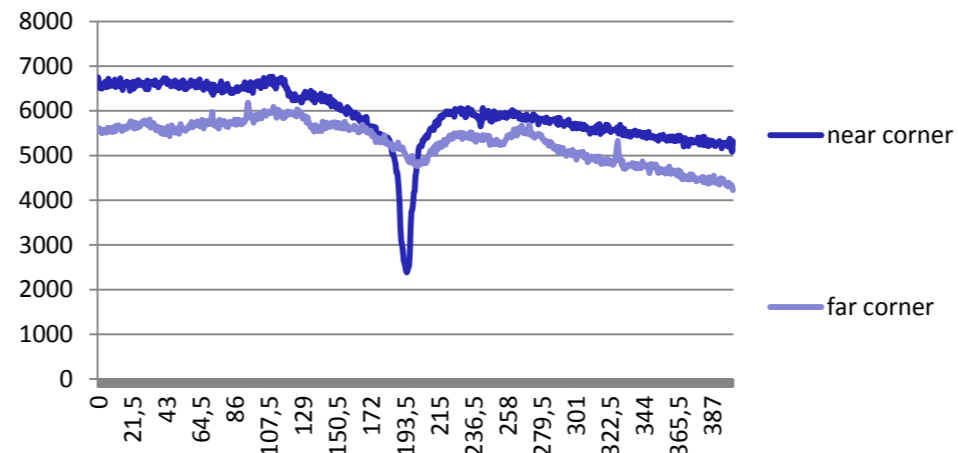
Position green



Intensity UV



Intensity green



	Peak Position	Height	Width
UV near	517,908	57,5835	9,10453
UV far	516,896	34,0553	10,4628
Green near	520,106	4526,09	4,4084
Green far	519,614	5612,84	5,1018

- Using the green laser it's possible to detect all of the four peaks of the structure like in the reference: the differences is due to the different process condition. In wf 02 there are all the four peaks in the center, due to the greater concentration of Ge and different thermal budget. On the laser annealed samples, at the edge of the laser spot, the higher concentration of Ge is caught by the Raman and it's due to reduced annealing and diffusion.
- Using the UV laser it's possible to see the peak of Si-Si in SiGe: the strong shift of the peaks in the center measurement and in the edge measurement shows the big tensile strain in the structure, due to the presence of Ge. The UV laser is more sensitive to this shift instead of green laser because of the smaller penetration depth.
- The crystalline structure are well defined and it improves using more thermal power, like the narrower width shows.
- The edge and the center of the square in wf 05 shows differences in structure and phases.



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